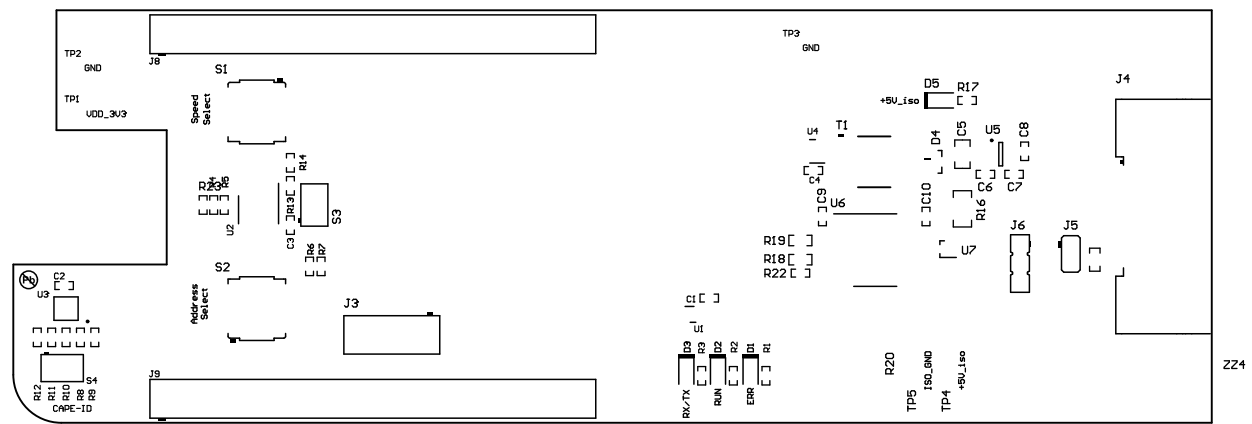


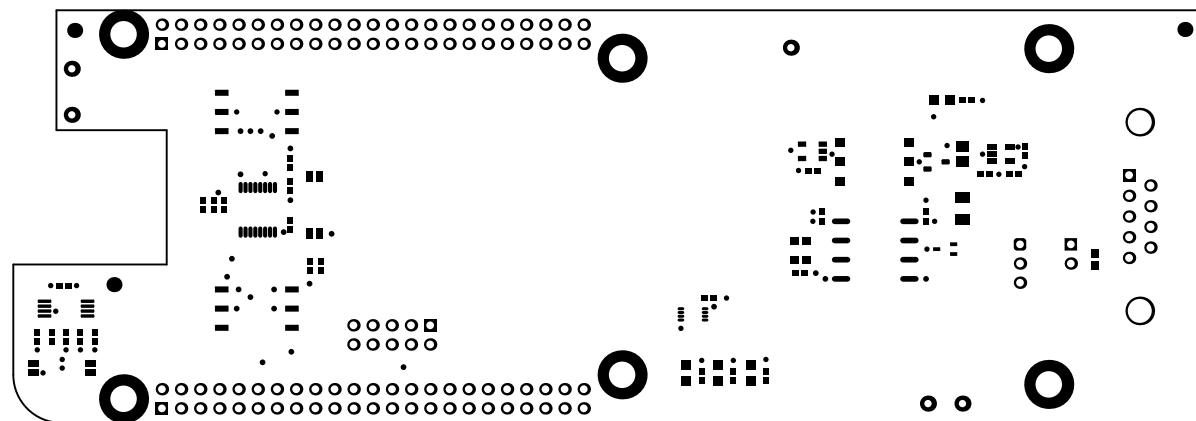
221

223 222



LBL1 Logo3
 For evaluation only; not FCC approved for resale.

ALL ARTWORK VIEWED FROM TOP SIDE BOARD #: TIDA-01406 REV: E1 SUN REV: Not In VersionControl
 LAYER NAME = Top Overlay TID #: TIDA-01406
 PLOT NAME = Top Overlay GENERATED : 3/27/2017 9:13:00 AM TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Top Solder

PLOT NAME = Top Solder Mask

BOARD #: TIDA-01406

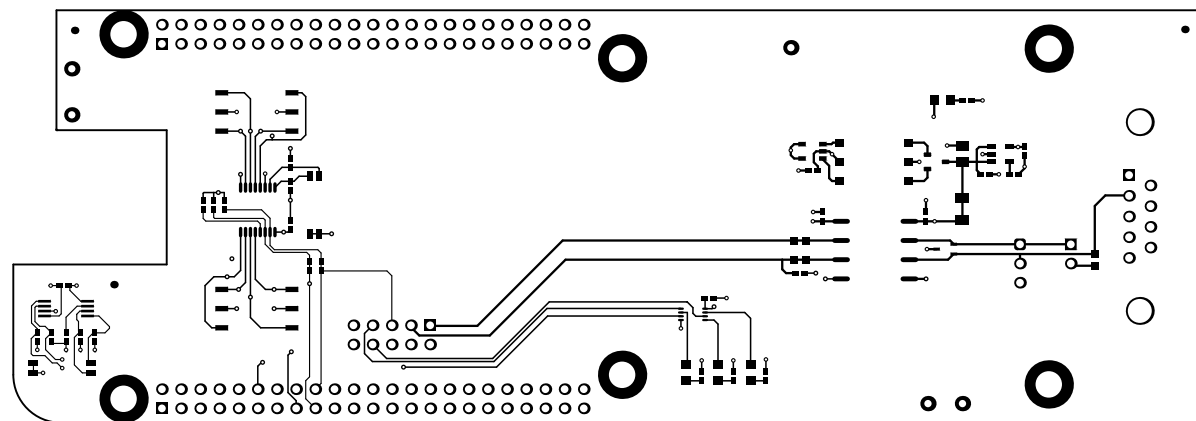
REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-01406

GENERATED : 3/27/2017 9:13:02 AM

TEXAS INSTRUMENTS



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1		8.00mil	4.2	
5	GND	Copper	1.40mil		
6	Dielectric 2	FR-4	40.00mil	4.2	
7	VDD	Copper	1.40mil		
8	Dielectric 3		8.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Top Layer

PLOT NAME = Top Layer

BOARD #: TIDA-01406

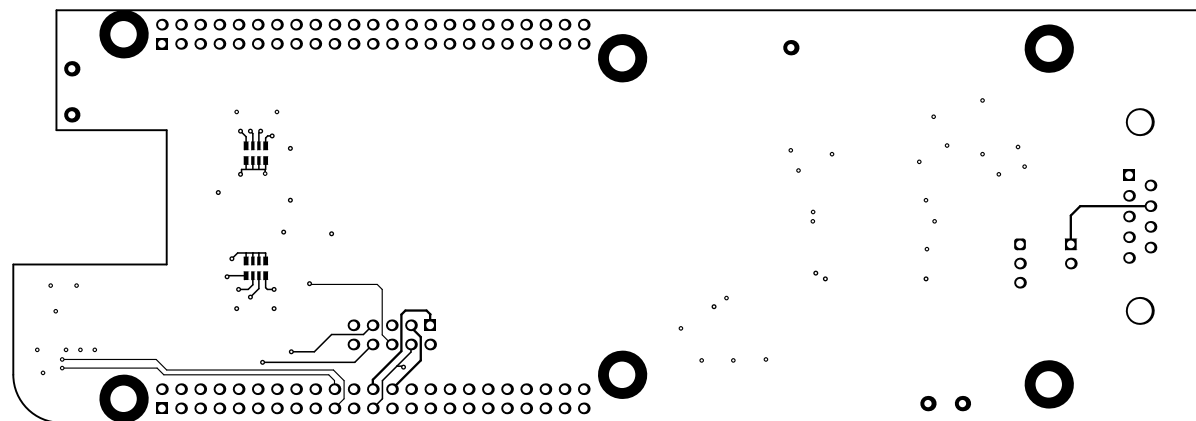
REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-01406

GENERATED : 3/27/2017 9:13:03 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Bottom Layer

PLOT NAME = Bottom Layer

BOARD #: TIDA-01406

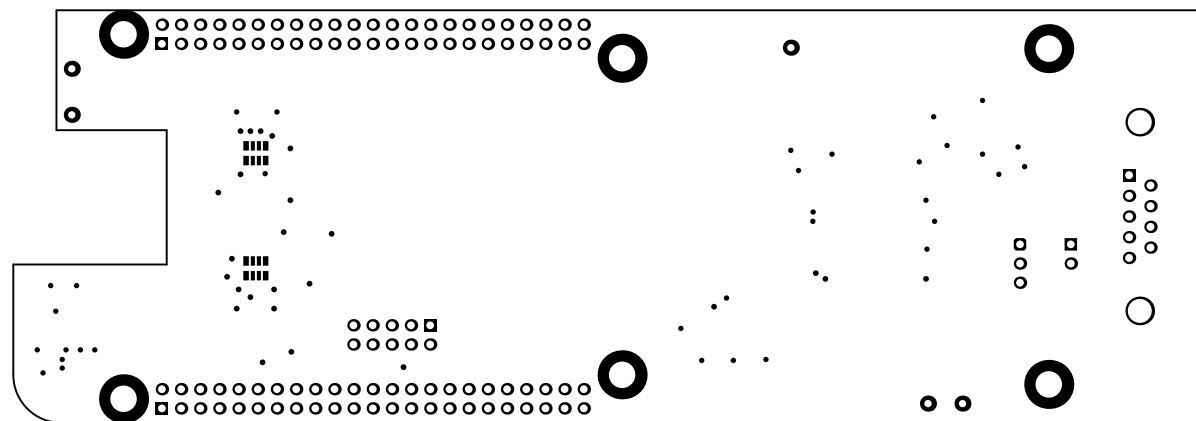
REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-01406

GENERATED : 3/27/2017 9:13:05 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Bottom Solder

PLOT NAME = Bottom Solder Mask

BOARD #: TIDA-01406

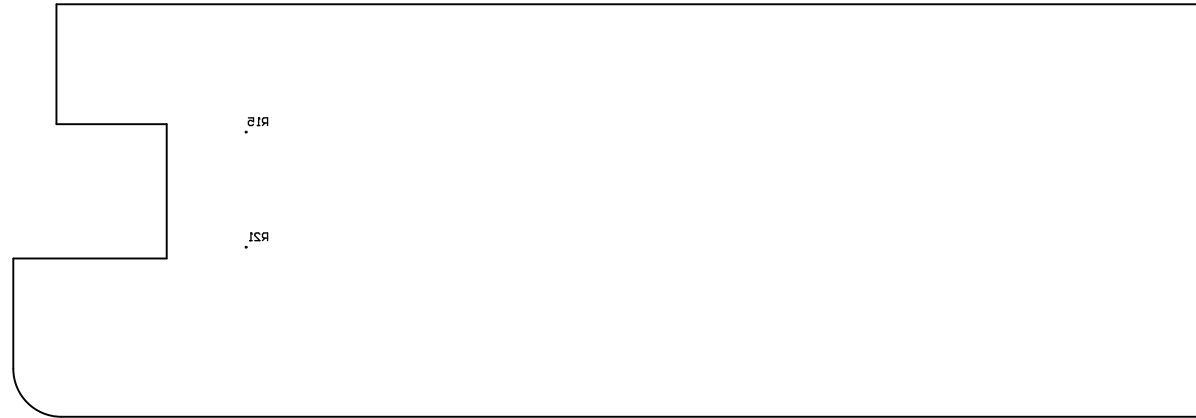
REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-01406

GENERATED : 3/27/2017 9:13:06 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Bottom Overlay

PLOT NAME = Bottom Overlay

BOARD #: TIDA-01406

REV: E1

SUN REV: Not In VersionControl

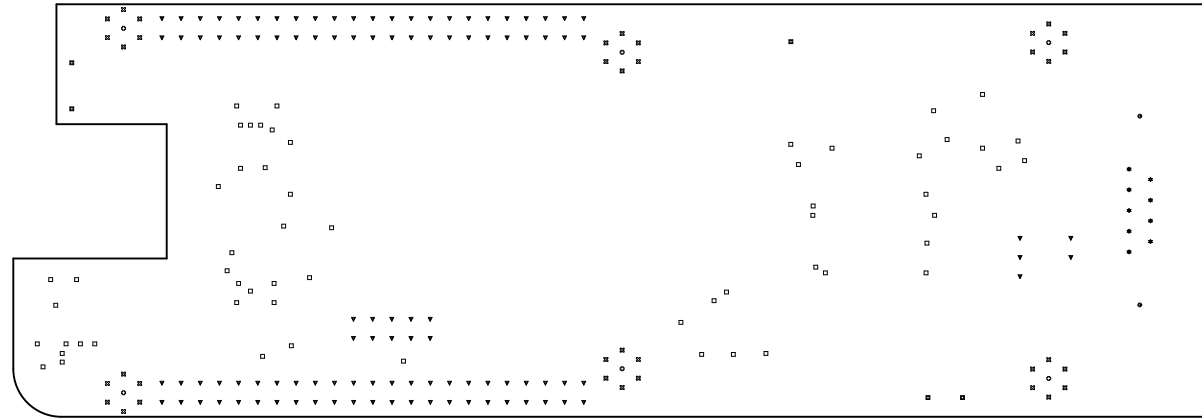
TID #: TIDA-01406

GENERATED : 3/27/2017 9:13:08 AM

TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	59	12.00mil (0.305mm)	PTH	Round

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	59	12.00mil (0.305mm)	PTH	Round
⊠	36	19.69mil (0.500mm)	PTH	Round
■	5	37.99mil (0.965mm)	PTH	Round
▼	107	40.16mil (1.020mm)	PTH	Round
★	9	40.94mil (1.040mm)	PTH	Round
●	2	124.80mil (3.170mm)	PTH	Round
⊙	6	137.80mil (3.500mm)	PTH	Round
Z24 Total				



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Drill Drawing

PLOT NAME = Drill Drawing

BOARD #: TIDA-01406

TID #: TIDA-01406

GENERATED : 3/27/2017

REV: E1

9:13:09 AM

SUN REV: Not In VersionControl

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = M2 Board Dimensions
PLOT NAME = Board Dimensions

BOARD #: TIDA-01406 REV: E1 SUN REV: Not In VersionControl
TID #: TIDA-01406
GENERATED : 3/27/2017 9:13:11 AM TEXAS INSTRUMENTS

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